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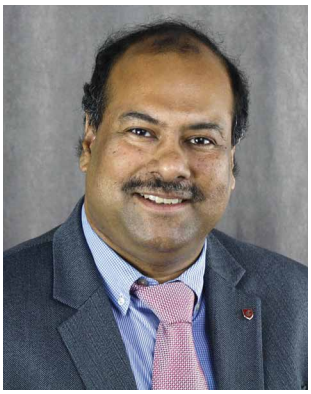

Machine Learning for CAD/EDA

The articles in this issue are divided into two groups: 1) the first group is a Special Issue on Machine Learning for CAD/EDA and 2) the second group consists of a tutorial article and a general interest article.

The highlight of this issue is the Special Issue on Machine Learning for CAD/EDA. Machine learning has been successfully employed in various stages of the integrated circuit design flow. This special issue consists of eight papers from both academia and industry addressing the broad topic of machine learning for CAD/EDA. We thank the guest editors Ulf Schlichtmann, Bei Yu, Bing Li, and Raviv Gal for making this special issue possible.

In this issue, we also include a tutorial article and a general interest article, titled, respectively, as follows: 1) "Enabling High-Level Design Strategies for High-Throughput and Low-Power NB-LDPC Decoders" and 2) "Fully Microstrip Three-Port Circuit Bandpass NGD Design and Test."

This issue also contains two conference reports. The first is a report on the International Symposium on Low-Power Electronics and Design (ISLPED) 2022. The second one is a report on Embedded Systems Week (ESWEEK) 2022.

A distinguishing feature of this issue is the interview with Janet Olson, who is the Vice President of Engineering at Cadence Designs Systems. We thank D&T editorial board member Nicola Nicolici for conducting the interview.

Many thanks to Scott Davidson for The Last Byte article titled "Training Data Sets: The Source of Our Woes?"

I hope you enjoy reading this issue of *IEEE Design&Test*.

■

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Digital Object Identifier 10.1109/MDAT.2022.3227524
Date of current version: 20 January 2023.

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